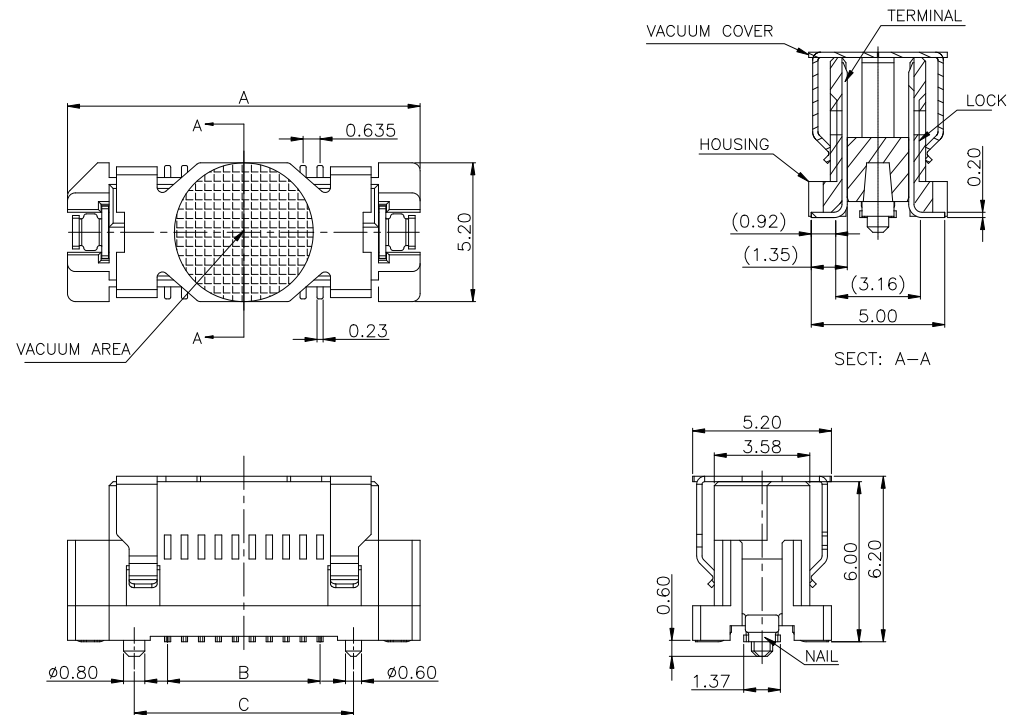


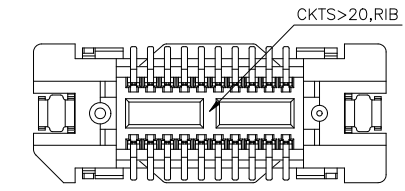
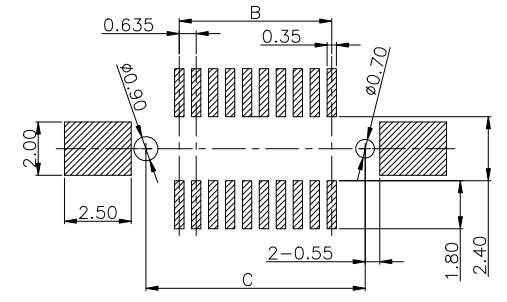
1
2
3
4
5



1. MATERIAL:
 - 1.1 INSULATOR: LCP, UL 94V-0.
INSULATOR COLOR: SEE ORDER INFORMATION.
 - 1.2 CONTACT: PHOSPHOR BRONZE, SELECTIVE GOLD (SEE ORDER INFORMATION)
PLATED IN CONTACT AREA, 40u" MIN TIN PLATED IN
SOLDER AREA, 30u" MIN. NICKEL UNDERPLATED OVERALL.
 - 1.3 NAIL: COPPER ALLOY, 40u" MIN TIN PLATED ON SURFACE
30u" MIN. NICKEL UNDERPLATED OVERALL.
 - 1.4 VACUUM COVER: STAINLESS STEEL.
2. SPECIFICATIONS:
 - 2.1 CURRENT RATING: 0.5A.
 - 2.2 CONTACT RESISTANCE: 50mΩ MAX.
 - 2.3 INSULATION RESISTANCE: 1000MΩ MIN.
 - 2.4 DIELECTRIC WITHSTANDING VOLTAGE: AC 250V PER MINUTE.
 - 2.5 OPERATING TEMPERATURE: -40°C~+105°C.
3. NOTES:
 - 3.1 THIS COMPONENT AND ITS HOMOGENEOUS
SUBCOMPONENTS ARE RoHS COMPLIANT.
 - 3.2 RESISTANCE TO SOLDERING HEAT: 265°C FOR 10 SECONDS.

4. SOLDER TAIL COPLANARITY 0.10mm MAX.
5. ORDER INFORMATION
BB226DB X 2 SX - 2XX D
INSULATOR COLOR: J
A: NATURE
B: BLACK
J: BROWN
CONTACT PLATED:
S1: GOLD FLASH
S2: 3u" GOLD
S3: 5u" GOLD
S4: 10u" GOLD
S5: 15u" GOLD
S6: 30u" GOLD
S7: 50u" GOLD
NO. OF CONTACTS:
210: 2*10 PINS=20 PINS
215: 2*15 PINS=30 PINS
~ ~
270: 2*70 PINS=140 PINS
280: 2*80 PINS=160 PINS

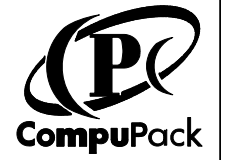
NO	52.67	50.165	57.67	160	---
	46.32	43.815	51.32	140	---
	39.97	37.465	44.97	120	---
	33.62	31.115	38.62	100	---
	30.45	27.94	35.45	90	---
	27.27	24.765	32.27	80	---
YES	24.1	21.59	29.1	70	---
	20.92	18.415	25.92	60	---
	17.75	15.24	22.75	50	---
	14.57	12.065	19.57	40	OK
	11.4	8.89	16.4	30	---
	8.22	5.715	13.22	20	---
LOCK	C	B	A	CONTACTS AVAILABLE	



PRELIMINARY
Subject to Change without notice

DIM.		TOL.		TITLE:	
X				BOARD TO BOARD PITCH 0.635mm MALE SMT VERTICAL TYPE	
X.X		±0.30		DWG. NO.:	
X.XX		±0.25		C-BB226DBX2SX-2XXD	
X.XXX		±0.15		DRAWN: GK	
GENERAL ANGLE:		±3°		PART NO.:	
				BB226DBX2SX-2XXD	
				CHECKED: Kevin	
				APPROVED: Peter	
				RFQ NO.:	
				Q1108067	

UNIT:	SCALE:	SHEET:	DWG. SIZE:	LAYER:	APPROVED:	RFQ NO.:
mm	none	1 OF 1	A4	CA059	Peter	Q1108067



REVISIONS